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Team Nexperia

PBSS5240X

40 V, 2 A PNP low V_{CEsat} (BISS) transistor

19 October 2012

Product data sheet

1. Product profile

1.1 General description

PNP low V_{CEsat} Breakthrough In Small Signal (BISS) transistor in a medium power and flat lead SOT89 Surface-Mounted Device (SMD) plastic package. NPN complement: PBSS4240X.

1.2 Features and benefits

- Low collector-emitter saturation voltage V_{CEsat}
- High collector current capability I_C and I_{CM}
- High efficiency due to less heat generation

1.3 Applications

- DC-to-DC conversion
- Supply line switching
- Battery charger
- LCD backlighting
- Driver in low supply voltage applications (e.g. lamps and LEDs)
- Inductive load driver (e.g. relays, buzzers and motors)

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CEO}	collector-emitter voltage	open base	-	-	-40	V
I _C	collector current		-	-	-2	A
I _{CM}	peak collector current		-	-	-3	A
R _{CEsat}	collector-emitter saturation resistance	I _C = -1 A; I _B = -100 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _{amb} = 25 °C	-	-	310	mΩ
I _{CRM}	repetitive peak collector current	t _p ≤ 20 ms; δ ≤ 0.33; pulsed	-	-	-2.5	A

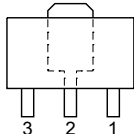
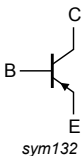


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2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	E	emitter	 <p style="text-align: center;">SOT89</p>	 <p style="text-align: center;">sym132</p>
2	C	collector		
3	B	base		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PBSS5240X	SOT89	plastic surface-mounted package; die pad for good heat transfer; 3 leads	SOT89

4. Marking

Table 4. Marking codes

Type number	Marking code
PBSS5240X	S48

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	-40	V
V_{CEO}	collector-emitter voltage	open base	-	-40	V
V_{EBO}	emitter-base voltage	open collector	-	-5	V
I_C	collector current		-	-2	A
I_{CRM}	repetitive peak collector current	$\delta \leq 0.33$; $t_p \leq 20$ ms; pulsed	-	-2.5	A
I_{CM}	peak collector current		-	-3	A
I_B	base current		-	-300	mA
I_{BM}	peak base current		-	-1	A
P_{tot}	total power dissipation		[1]	0.5	W
			[2]	0.95	W

Symbol	Parameter	Conditions		Min	Max	Unit
			[3]	-	1.35	W
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-65	150	°C
T_{stg}	storage temperature			-65	150	°C

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm².
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm².

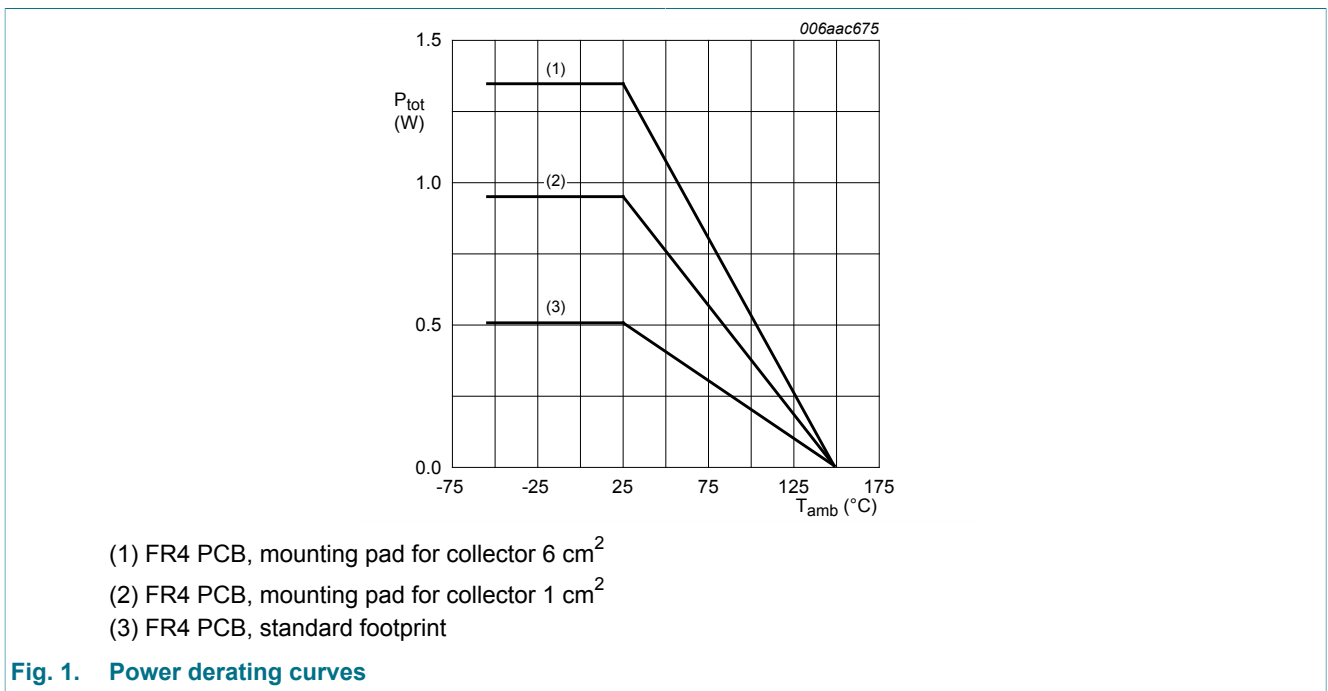


Fig. 1. Power derating curves

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	250	K/W
			[2]	-	-	132	K/W
			[3]	-	-	93	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	-	16	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm².
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm².

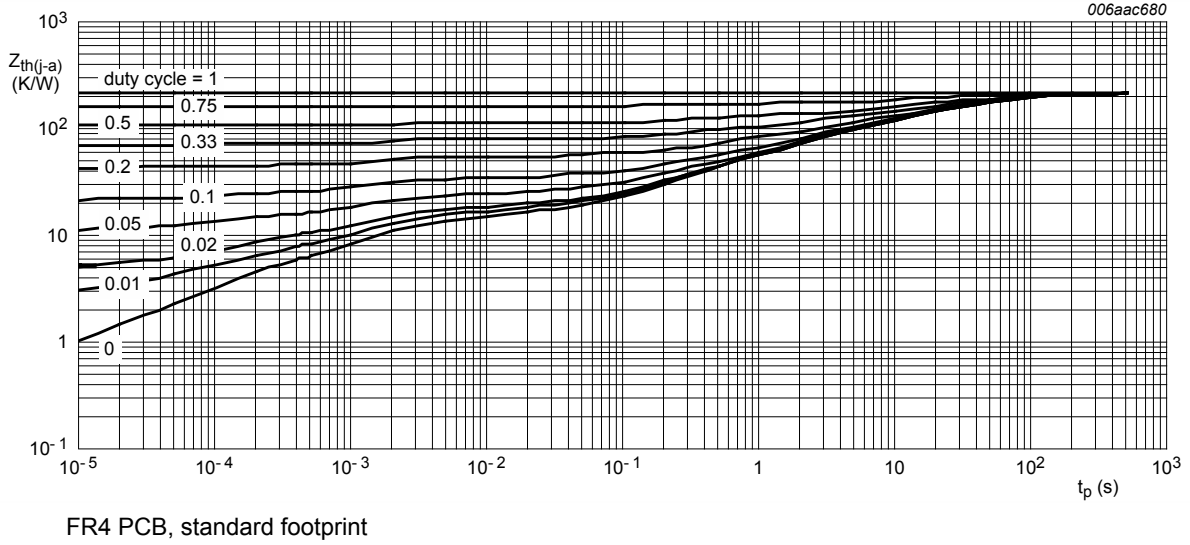


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

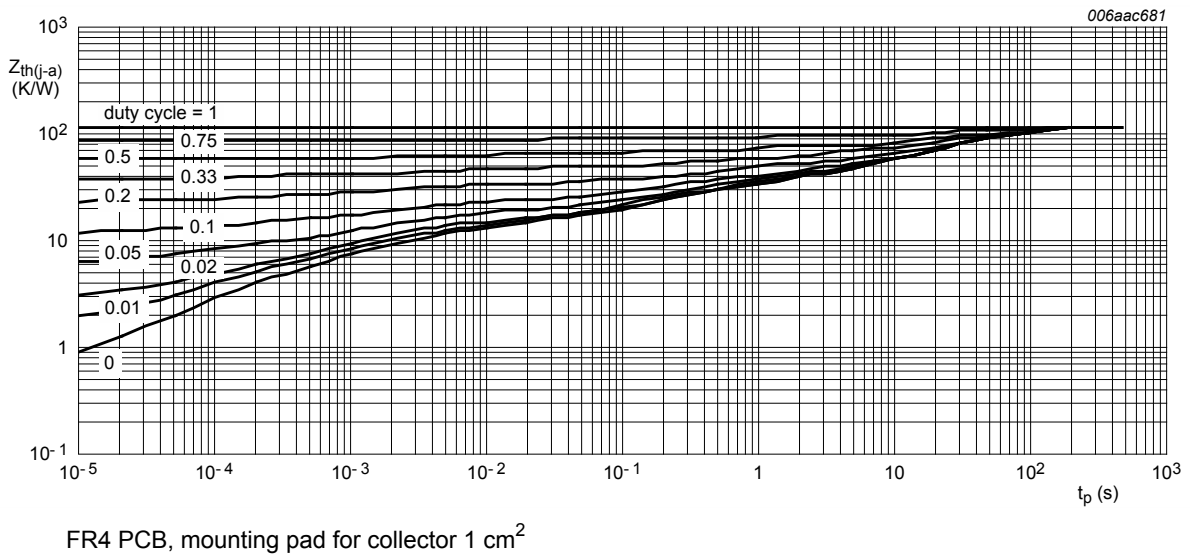
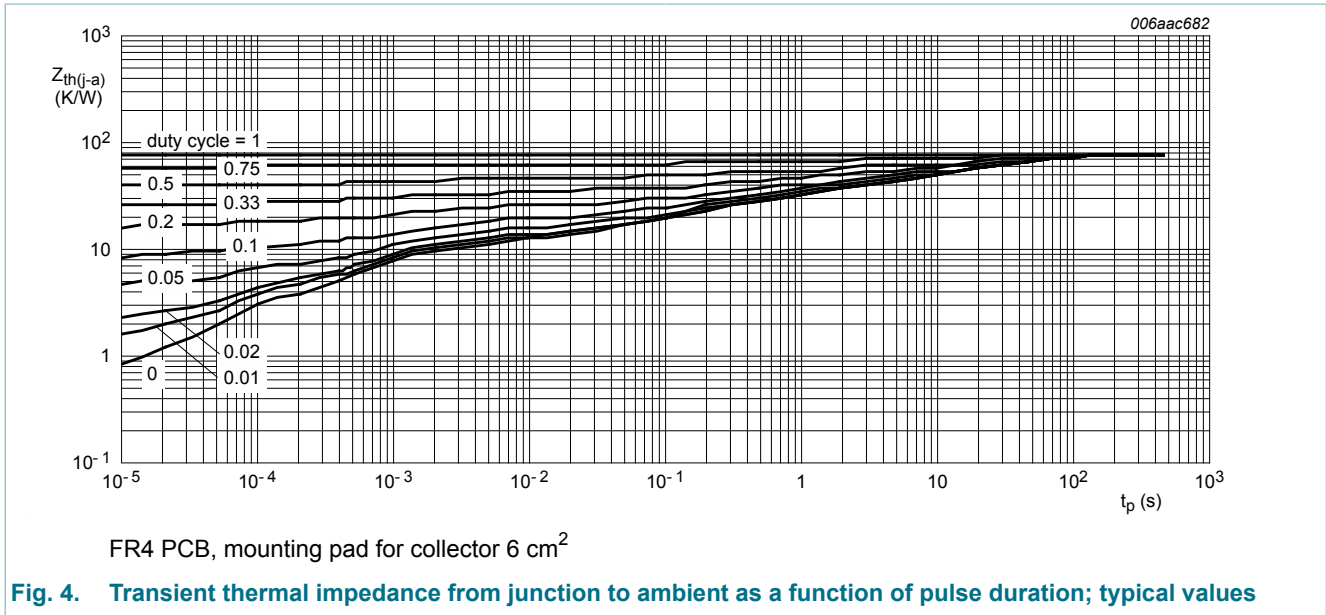


Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



7. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I _{CBO}	collector-base cut-off current	V _{CB} = -40 V; I _E = 0 A; T _{amb} = 25 °C	-	-	-100	nA
		V _{CB} = -40 V; I _E = 0 A; T _j = 150 °C	-	-	-50	μA
I _{CEO}	collector-emitter cut-off current	V _{CE} = -30 V; I _B = 0 A; T _{amb} = 25 °C	-	-	-100	nA
I _{EBO}	emitter-base cut-off current	V _{EB} = -5 V; I _C = 0 A; T _{amb} = 25 °C	-	-	-100	nA
h _{FE}	DC current gain	V _{CE} = -5 V; I _C = -1 mA; T _{amb} = 25 °C	300	-	-	
		V _{CE} = -5 V; I _C = -500 mA; T _{amb} = 25 °C	215	-	-	
		V _{CE} = -5 V; I _C = -1 A; T _{amb} = 25 °C	145	-	-	
		V _{CE} = -5 V; I _C = -2 A; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _{amb} = 25 °C	55	-	-	
V _{CEsat}	collector-emitter saturation voltage	I _C = -100 mA; I _B = -5 mA; T _{amb} = 25 °C	-	-	-140	mV
		I _C = -500 mA; I _B = -50 mA; T _{amb} = 25 °C	-	-	-170	mV
		I _C = -1 A; I _B = -100 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _{amb} = 25 °C	-	-	-310	mV
		I _C = -2 A; I _B = -200 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _{amb} = 25 °C	-	-	-630	mV
R _{CEsat}	collector-emitter saturation resistance	I _C = -1 A; I _B = -100 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _{amb} = 25 °C	-	-	310	mΩ

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{BEsat}	base-emitter saturation voltage	$I_C = -1\text{ A}$; $I_B = -100\text{ mA}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{amb} = 25\text{ }^\circ\text{C}$	-	-	-1.2	V
V_{BEon}	base-emitter turn-on voltage	$V_{CE} = -5\text{ V}$; $I_C = -1\text{ A}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{amb} = 25\text{ }^\circ\text{C}$	-	-	-1.1	V
f_T	transition frequency	$V_{CE} = -10\text{ V}$; $I_C = -50\text{ mA}$; $f = 100\text{ MHz}$; $T_{amb} = 25\text{ }^\circ\text{C}$	150	-	-	MHz
C_C	collector capacitance	$V_{CB} = -10\text{ V}$; $I_E = 0\text{ A}$; $i_e = 0\text{ A}$; $f = 1\text{ MHz}$; $T_{amb} = 25\text{ }^\circ\text{C}$	-	-	12	pF

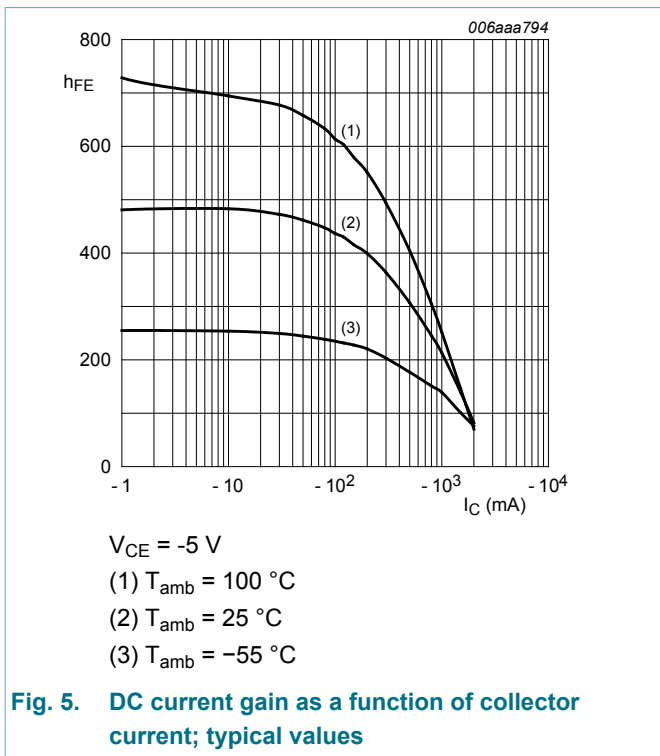


Fig. 5. DC current gain as a function of collector current; typical values

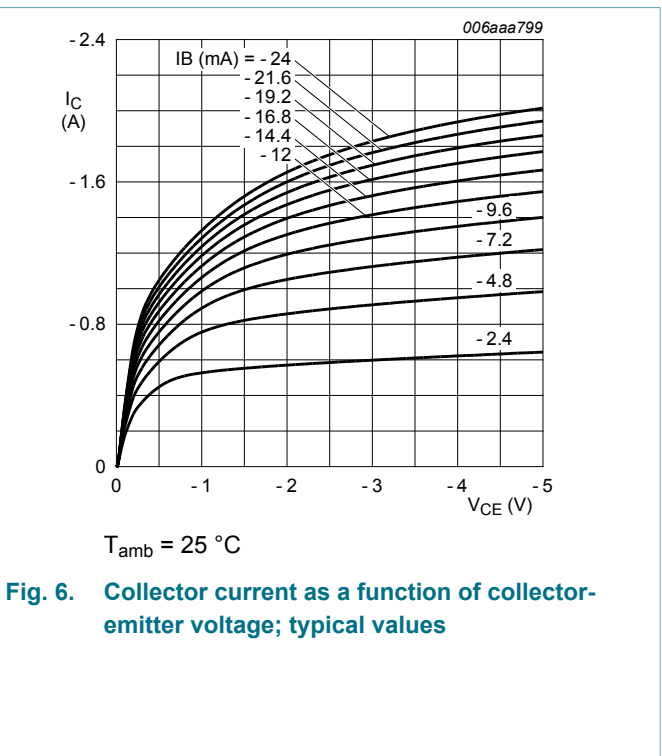
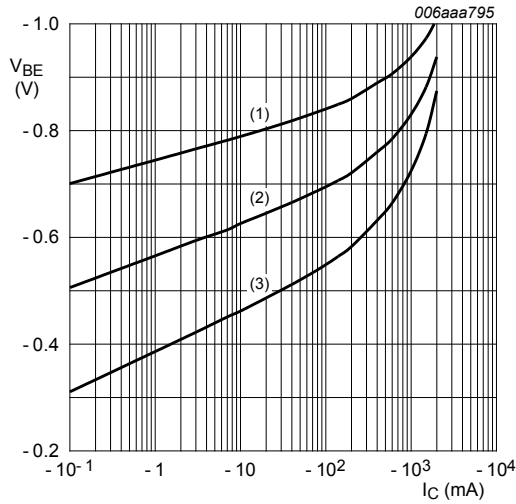
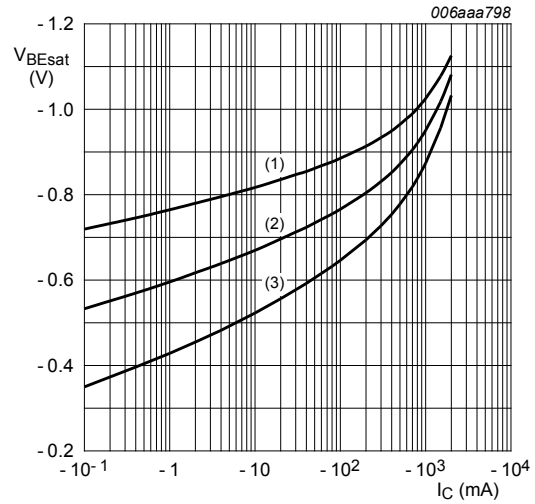


Fig. 6. Collector current as a function of collector-emitter voltage; typical values



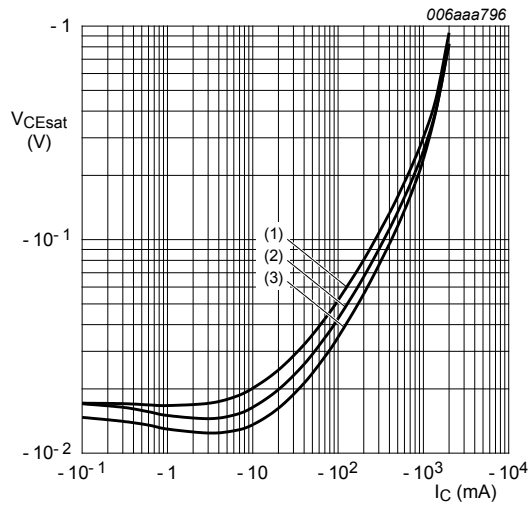
$V_{CE} = -5\text{ V}$
 (1) $T_{amb} = -55\text{ }^\circ\text{C}$
 (2) $T_{amb} = 25\text{ }^\circ\text{C}$
 (3) $T_{amb} = 100\text{ }^\circ\text{C}$

Fig. 7. Base-emitter voltage as a function of collector current; typical values



$I_C/I_B = 20$
 (1) $T_{amb} = -55\text{ }^\circ\text{C}$
 (2) $T_{amb} = 25\text{ }^\circ\text{C}$
 (3) $T_{amb} = 150\text{ }^\circ\text{C}$

Fig. 8. Base-emitter saturation voltage as a function of collector current; typical values



$I_C/I_B = 20$
 (1) $T_{amb} = 100\text{ }^\circ\text{C}$
 (2) $T_{amb} = 25\text{ }^\circ\text{C}$
 (3) $T_{amb} = -55\text{ }^\circ\text{C}$

Fig. 9. Collector-emitter saturation voltage as a function of collector current; typical values

8. Package outline

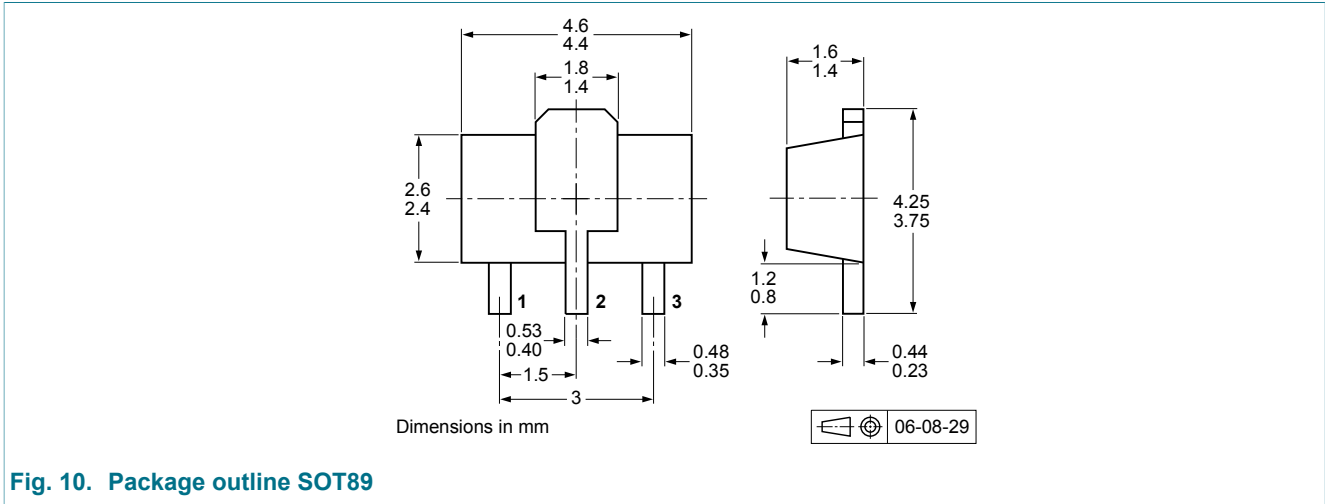


Fig. 10. Package outline SOT89

9. Soldering

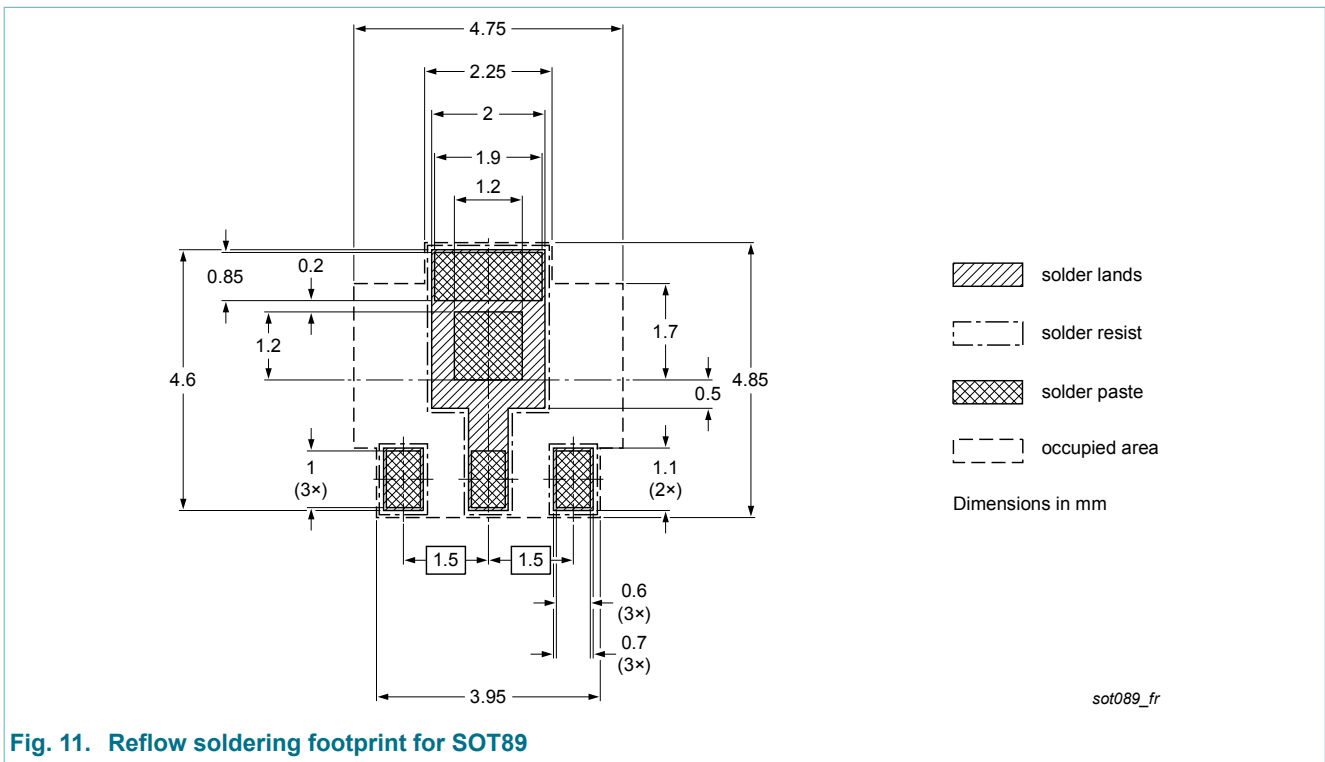


Fig. 11. Reflow soldering footprint for SOT89

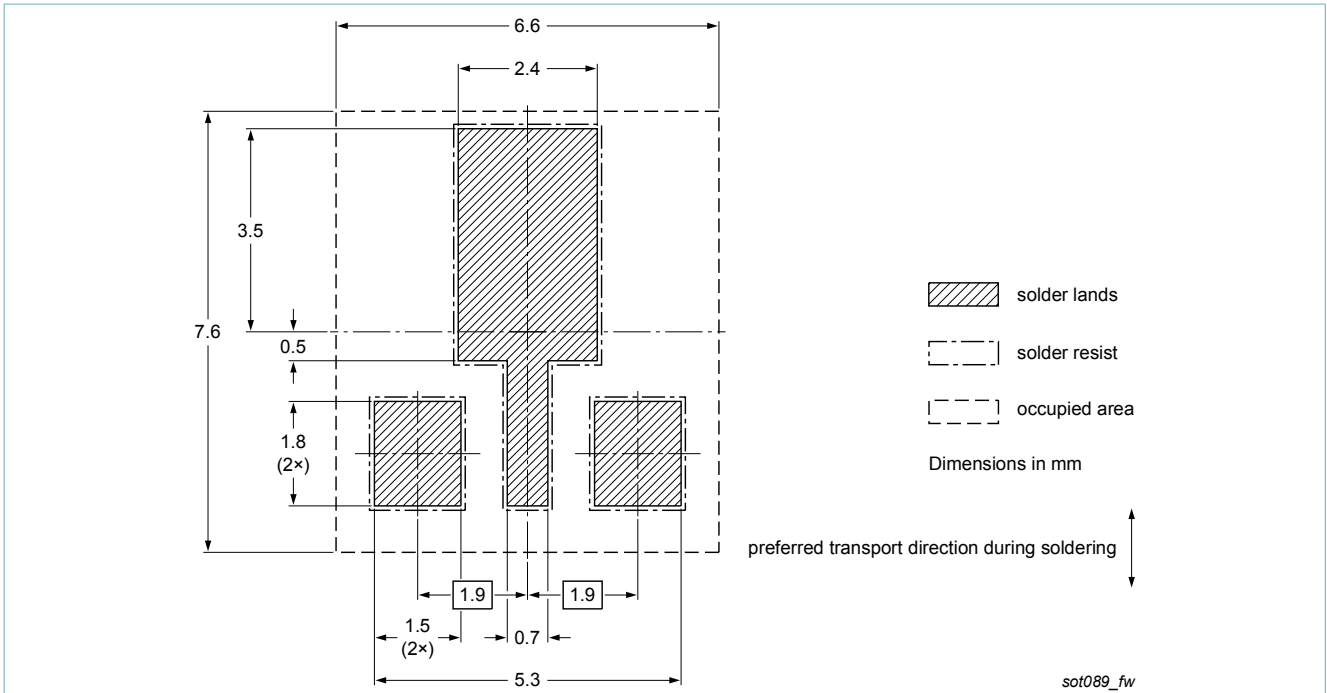


Fig. 12. Wave soldering footprint for SOT89

10. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PBSS5240X v.1	20121019	Product data sheet	-	-

11. Legal information

11.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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